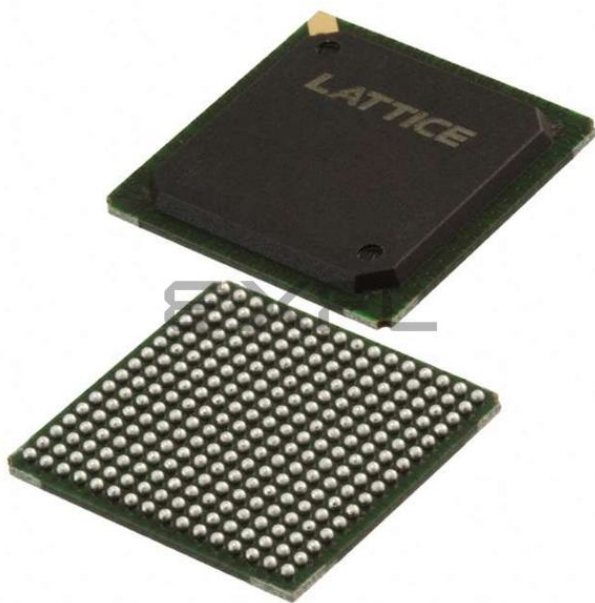




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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	512
Number of Gates	-
Number of I/O	192
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-512-192-10fac

Table 1. ispMACH 4A Device Features

3.3 V Devices								
Feature	M4A3-32	M4A3-64	M4A3-96	M4A3-128	M4A3-192	M4A3-256	M4A3-384	M4A3-512
Macrocells	32	64	96	128	192	256	384	512
User I/O options	32	32/64	48	64	96	128/160/192	160/192	160/192/256
t_{PD} (ns)	5.0	5.5	5.5	5.5	6.0	5.5	6.5	7.5
f_{CNT} (MHz)	182	167	167	167	160	167	154	125
t_{COS} (ns)	4.0	4.0	4.0	4.0	4.5	4.0	4.5	5.5
t_{SS} (ns)	3.0	3.5	3.5	3.5	3.5	3.5	3.5	5.0
Static Power (mA)	20	25/52	40	55	85	110/150	149/155	179
JTAG Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PCI Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

5 V Devices						
Feature	M4A5-32	M4A5-64	M4A5-96	M4A5-128	M4A5-192	M4A5-256
Macrocells	32	64	96	128	192	256
User I/O options	32	32	48	64	96	128
t_{PD} (ns)	5.0	5.5	5.5	5.5	6.0	6.5
f_{CNT} (MHz)	182	167	167	167	160	154
t_{COS} (ns)	4.0	4.0	4.0	4.0	4.5	5.0
t_{SS} (ns)	3.0	3.5	3.5	3.5	3.5	3.5
Static Power (mA)	20	25	40	55	74	110
JTAG Compliant	Yes	Yes	Yes	Yes	Yes	Yes
PCI Compliant	Yes	Yes	Yes	Yes	Yes	Yes

GENERAL DESCRIPTION

The ispMACH™ 4A family from Lattice offers an exceptionally flexible architecture and delivers a superior Complex Programmable Logic Device (CPLD) solution of easy-to-use silicon products and software tools. The overall benefits for users are a guaranteed and predictable CPLD solution, faster time-to-market, greater flexibility and lower cost. The ispMACH 4A devices offer densities ranging from 32 to 512 macrocells with 100% utilization and 100% pin-out retention. The ispMACH 4A families offer 5-V (M4A5-xxx) and 3.3-V (M4A3-xxx) operation.

ispMACH 4A products are 5-V or 3.3-V in-system programmable through the JTAG (IEEE Std. 1149.1) interface. JTAG boundary scan testing also allows product testability on automated test equipment for device connectivity.

All ispMACH 4A family members deliver First-Time-Fit and easy system integration with pin-out retention after any design change and refit. For both 3.3-V and 5-V operation, ispMACH 4A products can deliver guaranteed fixed timing as fast as 5.0 ns t_{PD} and 182 MHz f_{CNT} through the SpeedLocking feature when using up to 20 product terms per output (Table 2).

Table 2. ispMACH 4A Speed Grades

Device	Speed Grade							
	-5	-55	-6	-65	-7	-10	-12	-14
M4A3-32 M4A5-32	C				C, I	C, I	I	
M4A3-64/32 M4A5-64/32		C			C, I	C, I	I	
M4A3-64/64		C			C, I	C, I	I	
M4A3-96 M4A5-96		C			C, I	C, I	I	
M4A3-128 M4A5-128		C			C, I	C, I	I	
M4A3-192 M4A5-192			C		C, I	C, I	I	
M4A3-256/128		C		C	C, I	C, I	I	
M4A5-256/128				C	C	C, I	I	
M4A3-256/192 M4A3-256/160					C	C, I	I	
M4A3-384				C		C, I	C, I	I
M4A3-512					C	C, I	C, I	I

Note:

1. C = Commercial, I = Industrial

The ispMACH 4A family offers 20 density-I/O combinations in Thin Quad Flat Pack (TQFP), Plastic Quad Flat Pack (PQFP), Plastic Leaded Chip Carrier (PLCC), Ball Grid Array (BGA), fine-pitch BGA (fpBGA), and chip-array BGA (caBGA) packages ranging from 44 to 388 pins (Table 3). It also offers I/O safety features for mixed-voltage designs so that the 3.3-V devices can accept 5-V inputs, and 5-V devices do not overdrive 3.3-V inputs. Additional features include Bus-Friendly inputs and I/Os, a programmable power-down mode for extra power savings and individual output slew rate control for the highest speed transition or for the lowest noise transition.

Table 3. ispMACH 4A Package and I/O Options (Number of I/Os and dedicated inputs in Table)

3.3 V Devices								
Package	M4A3-32	M4A3-64	M4A3-96	M4A3-128	M4A3-192	M4A3-256	M4A3-384	M4A3-512
44-pin PLCC	32+2	32+2						
44-pin TQFP	32+2	32+2						
48-pin TQFP	32+2	32+2						
100-pin TQFP		64+6	48+8	64+6				
100-pin PQFP				64+6				
100-ball caBGA				64+6				
144-pin TQFP					96+16			
144-ball fpBGA					96+16			
208-pin PQFP						128+14, 160	160	160
256-ball fpBGA						128+14, 192	192	192
256-ball BGA						128+14	192	
388-ball fpBGA								256

5 V Devices						
Package	M4A5-32	M4A5-64	M4A5-96	M4A5-128	M4A5-192	M4A5-256
44-pin PLCC	32+2	32+2				
44-pin TQFP	32+2	32+2				
48-pin TQFP	32+2	32+2				
100-pin TQFP			48+8	64+6		
100-pin PQFP				64+6		
144-pin TQFP					96+16	
208-pin PQFP						128+14

FUNCTIONAL DESCRIPTION

The fundamental architecture of ispMACH 4A devices (Figure 1) consists of multiple, optimized PAL[®] blocks interconnected by a central switch matrix. The central switch matrix allows communication between PAL blocks and routes inputs to the PAL blocks. Together, the PAL blocks and central switch matrix allow the logic designer to create large designs in a single device instead of having to use multiple devices.

The key to being able to make effective use of these devices lies in the interconnect schemes. In the ispMACH 4A architecture, the macrocells are flexibly coupled to the product terms through the logic allocator, and the I/O pins are flexibly coupled to the macrocells due to the output switch matrix. In addition, more input routing options are provided by the input switch matrix. These resources provide the flexibility needed to fit designs efficiently.



17466G-001

Figure 1. ispMACH 4A Block Diagram and PAL Block Structure

Notes:

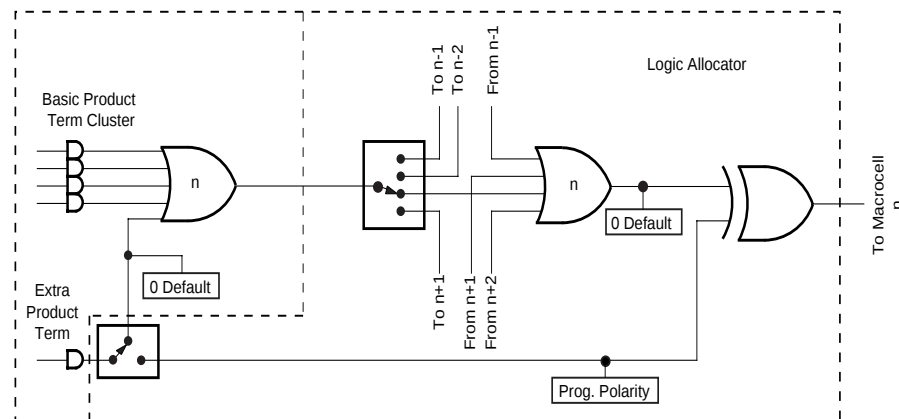
1. 16 for ispMACH 4A devices with 1:1 macrocell-I/O cell ratio (see next page).
2. Block clocks do not go to I/O cells in M4A(3,5)-32/32.
3. M4A(3,5)-192, M4A(3,5)-256, M4A3-384, and M4A3-512 have dedicated clock pins which cannot be used as inputs and do not connect to the central switch matrix.

Table 6. Logic Allocator for All ispMACH 4A Devices (except M4A(3,5)-32/32)

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M ₀	C ₀ , C ₁ , C ₂	M ₈	C ₇ , C ₈ , C ₉ , C ₁₀
M ₁	C ₀ , C ₁ , C ₂ , C ₃	M ₉	C ₈ , C ₉ , C ₁₀ , C ₁₁
M ₂	C ₁ , C ₂ , C ₃ , C ₄	M ₁₀	C ₉ , C ₁₀ , C ₁₁ , C ₁₂
M ₃	C ₂ , C ₃ , C ₄ , C ₅	M ₁₁	C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₄	C ₃ , C ₄ , C ₅ , C ₆	M ₁₂	C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄
M ₅	C ₄ , C ₅ , C ₆ , C ₇	M ₁₃	C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₆	C ₅ , C ₆ , C ₇ , C ₈	M ₁₄	C ₁₃ , C ₁₄ , C ₁₅
M ₇	C ₆ , C ₇ , C ₈ , C ₉	M ₁₅	C ₁₄ , C ₁₅

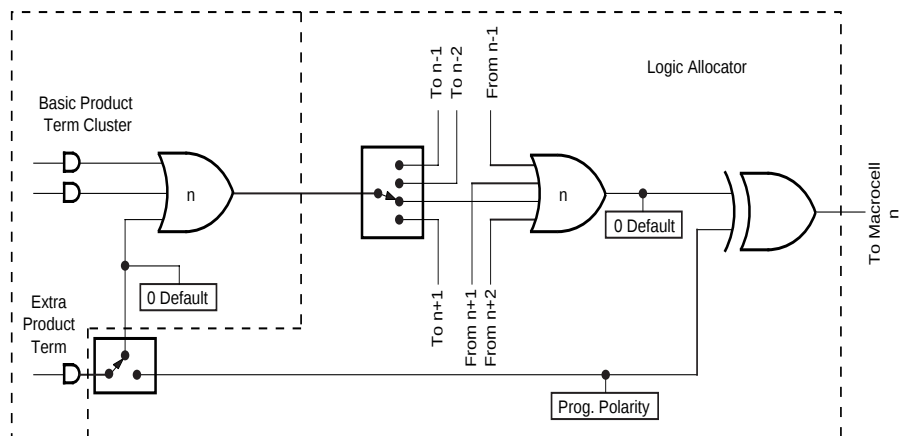
Table 7. Logic Allocator for M4A(3,5)-32/32

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M ₀	C ₀ , C ₁ , C ₂	M ₈	C ₈ , C ₉ , C ₁₀
M ₁	C ₀ , C ₁ , C ₂ , C ₃	M ₉	C ₈ , C ₉ , C ₁₀ , C ₁₁
M ₂	C ₁ , C ₂ , C ₃ , C ₄	M ₁₀	C ₉ , C ₁₀ , C ₁₁ , C ₁₂
M ₃	C ₂ , C ₃ , C ₄ , C ₅	M ₁₁	C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₄	C ₃ , C ₄ , C ₅ , C ₆	M ₁₂	C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄
M ₅	C ₄ , C ₅ , C ₆ , C ₇	M ₁₃	C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₆	C ₅ , C ₆ , C ₇	M ₁₄	C ₁₃ , C ₁₄ , C ₁₅
M ₇	C ₆ , C ₇	M ₁₅	C ₁₄ , C ₁₅



a. Synchronous Mode

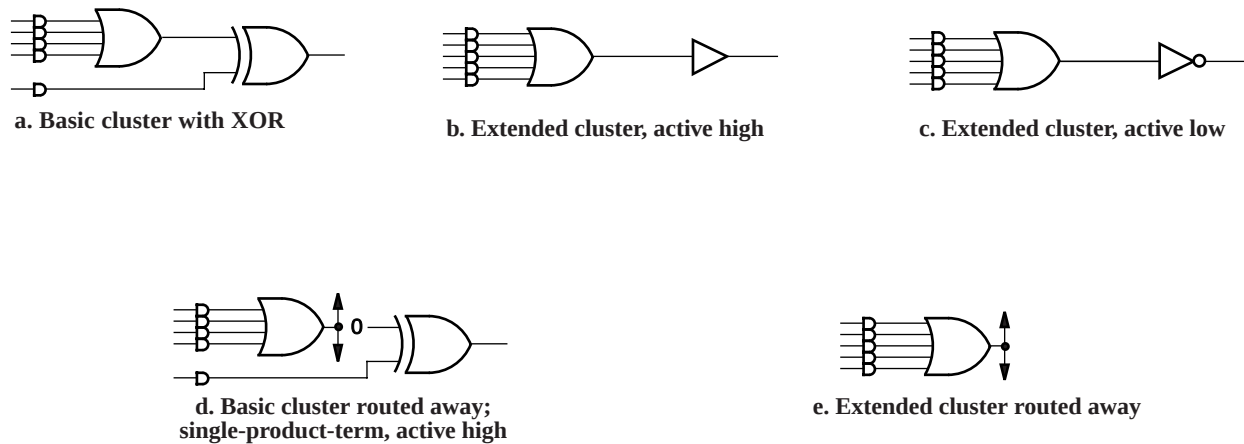
17466G-005



b. Asynchronous Mode

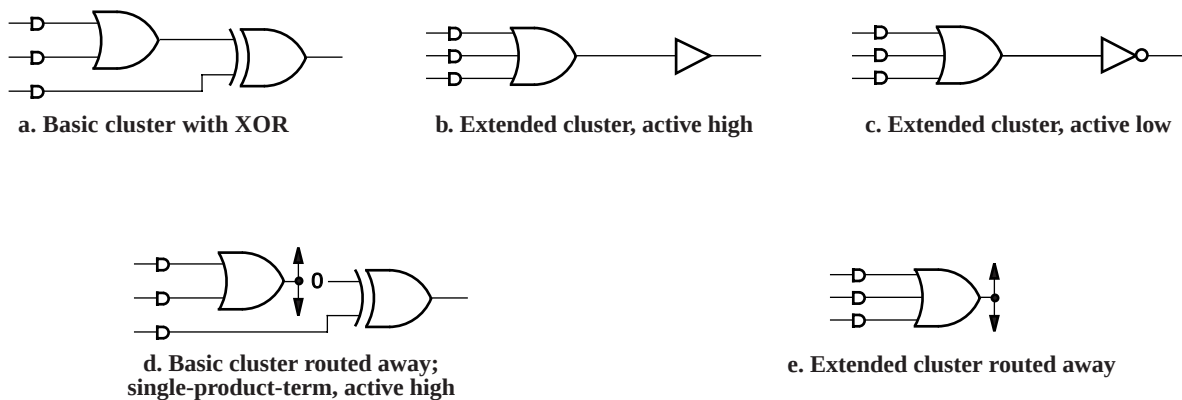
17466G-006

Figure 2. Logic Allocator: Configuration of Cluster “n” Set by Mode of Macrocell “n”



17466G-007

Figure 3. Logic Allocator Configurations: Synchronous Mode



17466G-008

Figure 4. Logic Allocator Configurations: Asynchronous Mode

Note that the configuration of the logic allocator has absolutely no impact on the speed of the signal. All configurations have the same delay. This means that designers do not have to decide between optimizing resources or speed; both can be optimized.

If not used in the cluster, the extra product term can act in conjunction with the basic cluster to provide XOR logic for such functions as data comparison, or it can work with the D-,T-type flip-flop to provide for J-K, and S-R register operation. In addition, if the basic cluster is routed to another macrocell, the extra product term is still available for logic. In this case, the first XOR input will be a logic 0. This circuit has the flexibility to route product terms elsewhere without giving up the use of the macrocell.

Product term clusters do not “wrap” around a PAL block. This means that the macrocells at the ends of the block have fewer product terms available.

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M12, M13	I/O3, I/O4, I/O5, I/O6
M14, M15	I/O4, I/O5, I/O6, I/O7

I/O Cell	Available Macrocells
I/O0	M0, M1, M2, M3, M4, M5, M6, M7
I/O1	M2, M3, M4, M5, M6, M7, M8, M9
I/O2	M4, M5, M6, M7, M8, M9, M10, M11
I/O3	M6, M7, M8, M9, M10, M11, M12, M13
I/O4	M8, M9, M10, M11, M12, M13, M14, M15
I/O5	M0, M1, M10, M11, M12, M13, M14, M15
I/O6	M0, M1, M2, M3, M12, M13, M14, M15
I/O7	M0, M1, M2, M3, M4, M5, M14, M15

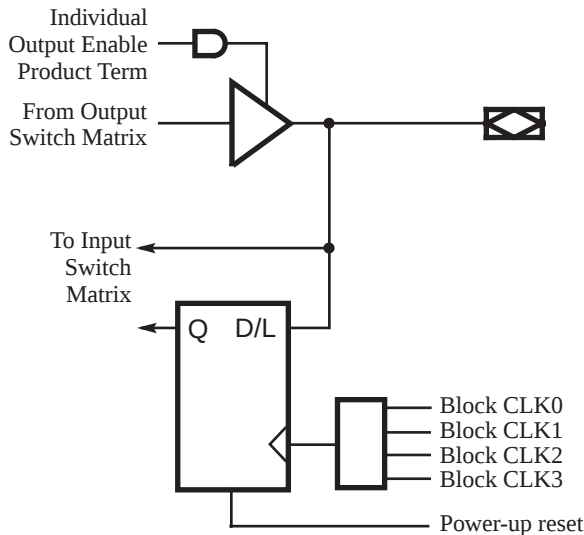
Table 11. Output Switch Matrix Combinations for M4A3-256/160 and M4A3-256/192

Macrocell	Routable to I/O Cells							
M0	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M1	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M2	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M3	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M4	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M5	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M6	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M7	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M8	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M9	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M10	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M11	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M12	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M13	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M14	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M15	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15

I/O Cell	Available Macrocells							
I/O0	M0	M1	M2	M3	M4	M5	M6	M7
I/O1	M0	M1	M2	M3	M4	M5	M6	M7
I/O2	M0	M1	M2	M3	M4	M5	M6	M7
I/O3	M0	M1	M2	M3	M4	M5	M6	M7
I/O4	M0	M1	M2	M3	M4	M5	M6	M7
I/O5	M0	M1	M2	M3	M4	M5	M6	M7
I/O6	M0	M1	M2	M3	M4	M5	M6	M7
I/O7	M0	M1	M2	M3	M4	M5	M6	M7

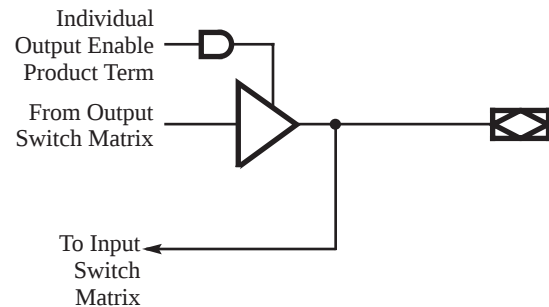
I/O Cell

The I/O cell (Figures 10 and 11) simply consists of a programmable output enable, a feedback path, and flip-flop (except ispMACH 4A devices with 1:1 macrocell-I/O cell ratio). An individual output enable product term is provided for each I/O cell. The feedback signal drives the input switch matrix.



17466G-017

Figure 10. I/O Cell for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio



17466G-018

Figure 11. I/O Cell for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio

The I/O cell (Figure 10) contains a flip-flop, which provides the capability for storing the input in a D-type register or latch. The clock can be any of the PAL block clocks. Both the direct and registered versions of the input are sent to the input switch matrix. This allows for such functions as “time-domain-multiplexed” data comparison, where the first data value is stored, and then the second data value is put on the I/O pin and compared with the previous stored value.

Note that the flip-flop used in the ispMACH 4A I/O cell is independent of the flip-flops in the macrocells. It powers up to a logic low.

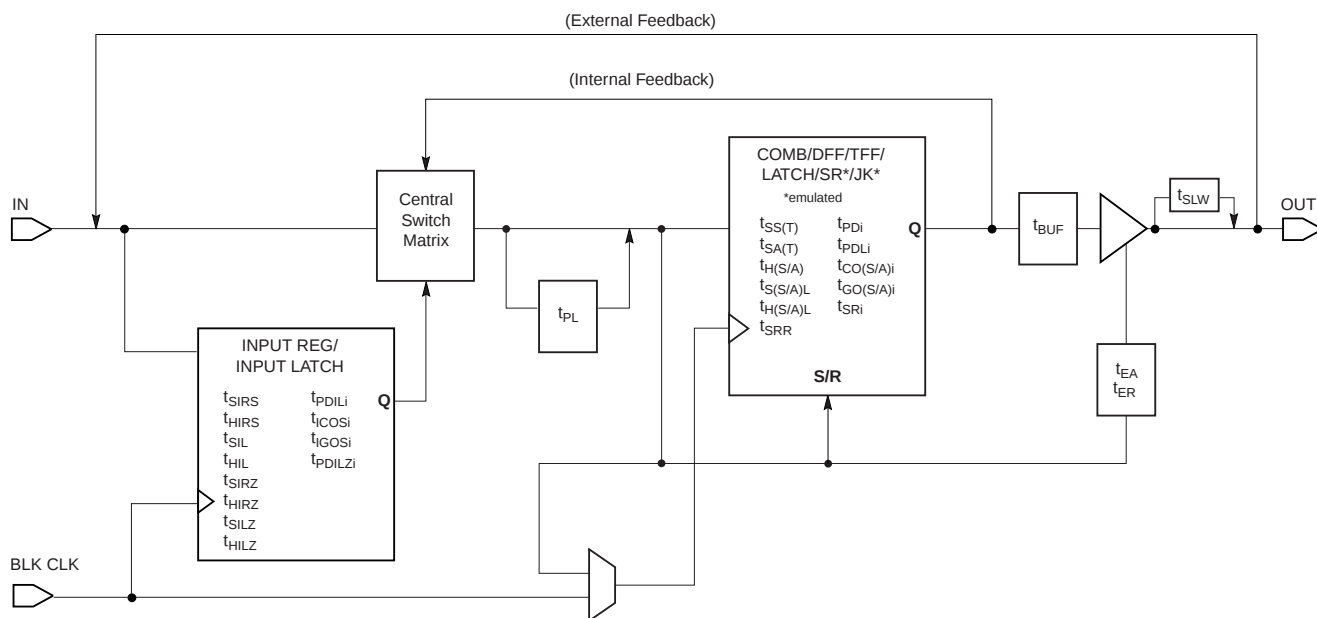
Zero-Hold-Time Input Register

The ispMACH 4A devices have a zero-hold-time (ZHT) fuse which controls the time delay associated with loading data into all I/O cell registers and latches. When programmed, the ZHT fuse increases the data path setup delays to input storage elements, matching equivalent delays in the clock path. When the fuse is erased, the setup time to the input storage element is minimized. This feature facilitates doing worst-case designs for which data is loaded from sources which have low (or zero) minimum output propagation delays from clock edges.

ispMACH 4A TIMING MODEL

The primary focus of the ispMACH 4A timing model is to accurately represent the timing in a ispMACH 4A device, and at the same time, be easy to understand. This model accurately describes all combinatorial and registered paths through the device, making a distinction between internal feedback and external feedback. A signal uses internal feedback when it is fed back into the switch matrix or block without having to go through the output buffer. The input register specifications are also reported as internal feedback. When a signal is fed back into the switch matrix after having gone through the output buffer, it is using external feedback.

The parameter, t_{BUF} , is defined as the time it takes to go from feedback through the output buffer to the I/O pad. If a signal goes to the internal feedback rather than to the I/O pad, the parameter designator is followed by an “i”. By adding t_{BUF} to this internal parameter, the external parameter is derived. For example, $t_{PD} = t_{PDi} + t_{BUF}$. A diagram representing the modularized ispMACH 4A timing model is shown in Figure 15. Refer to the application note entitled *MACH 4 Timing and High Speed Design* for a more detailed discussion about the timing parameters.



17466G-025

Figure 15. ispMACH 4A Timing Model

SPEEDLOCKING FOR GUARANTEED FIXED TIMING

The ispMACH 4A architecture allows allocation of up to 20 product terms to an individual macrocell with the assistance of an XOR gate without incurring additional timing delays.

The design of the switch matrix and PAL blocks guarantee a fixed pin-to-pin delay that is independent of the logic required by the design. Other competitive CPLDs incur serious timing delays as product terms expand beyond their typical 4 or 5 product term limits. Speed and SpeedLocking combine to give designs easy access to the performance required in today's designs.

weakly pulled up. For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

POWER MANAGEMENT

Each individual PAL block in ispMACH 4A devices features a programmable low-power mode, which results in power savings of up to 50%. The signal speed paths in the low-power PAL block will be slower than those in the non-low-power PAL block. This feature allows speed critical paths to run at maximum frequency while the rest of the signal paths operate in the low-power mode.

PROGRAMMABLE SLEW RATE

Each ispMACH 4A device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for the higher speed transition (3 V/ns) or for the lower noise transition (1 V/ns). For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise, and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed. The slew rate is adjusted independent of power.

POWER-UP RESET/SET

All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the control generator, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the control generator or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic, and the clock must be inactive until the reset delay time has elapsed.

SECURITY BIT

A programmable security bit is provided on the ispMACH 4A devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

HOT SOCKETING

ispMACH 4A devices are well-suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down MACH devices be minimal on active signals.

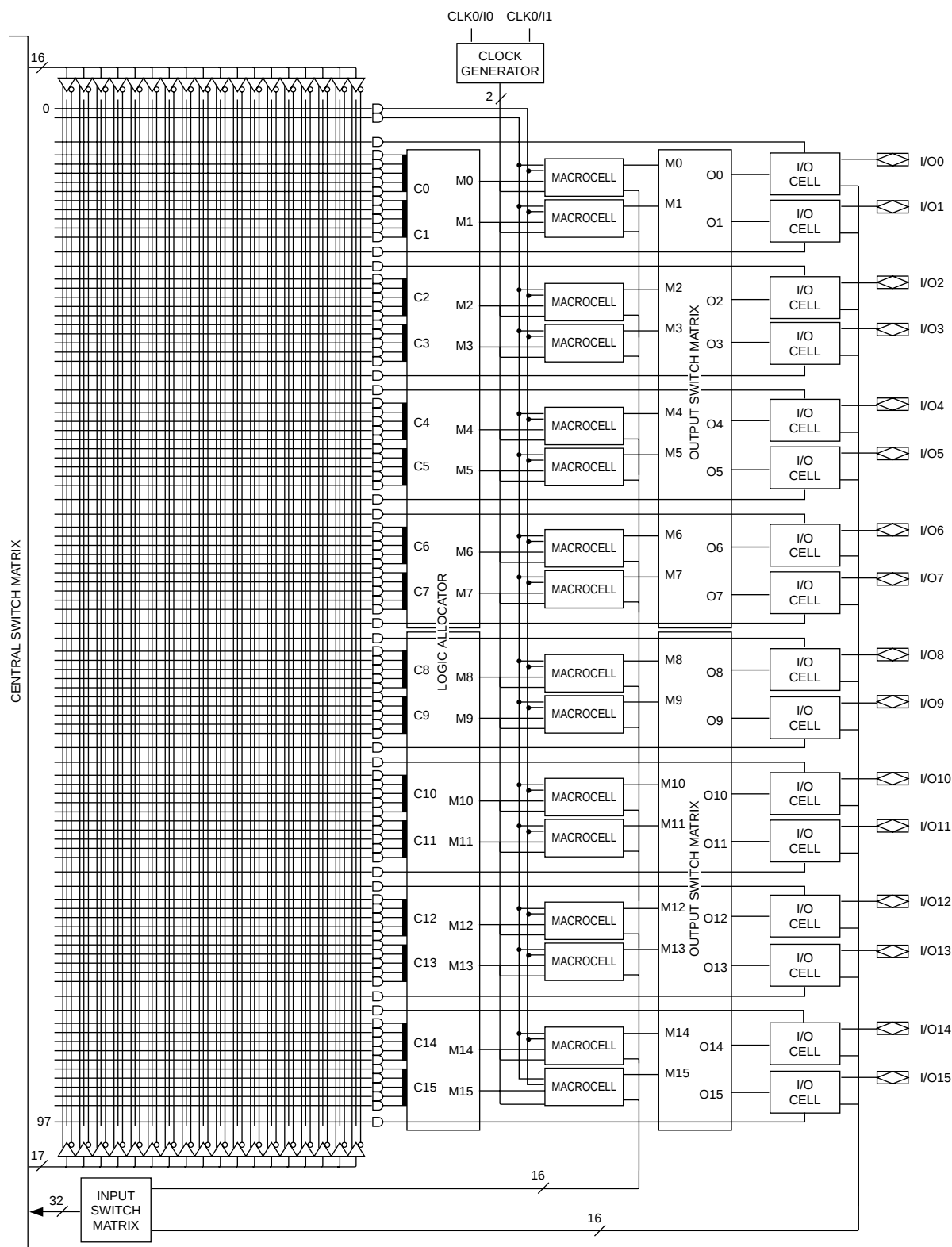
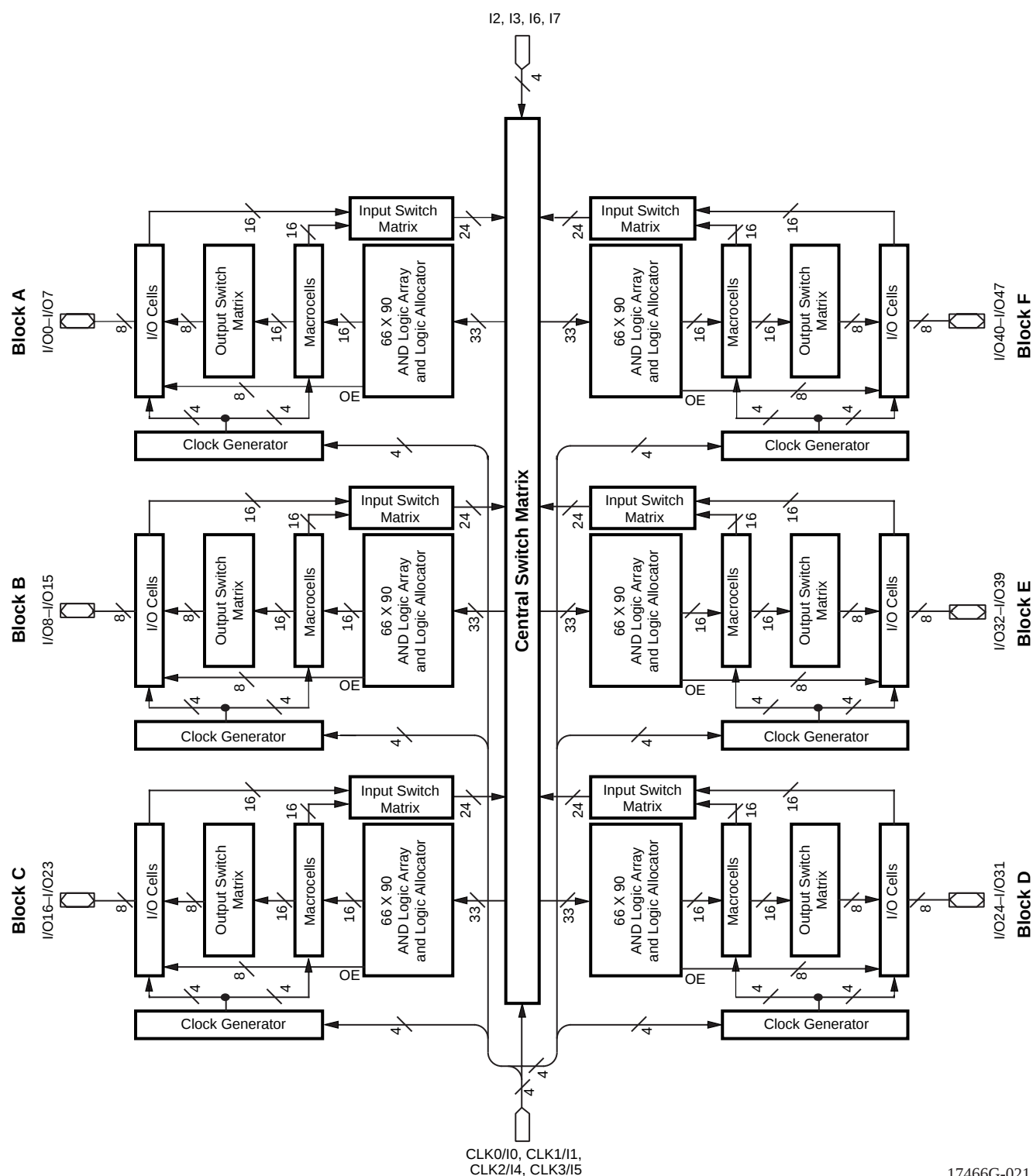


Figure 18. PAL Block for M4A (3,5)-32/32

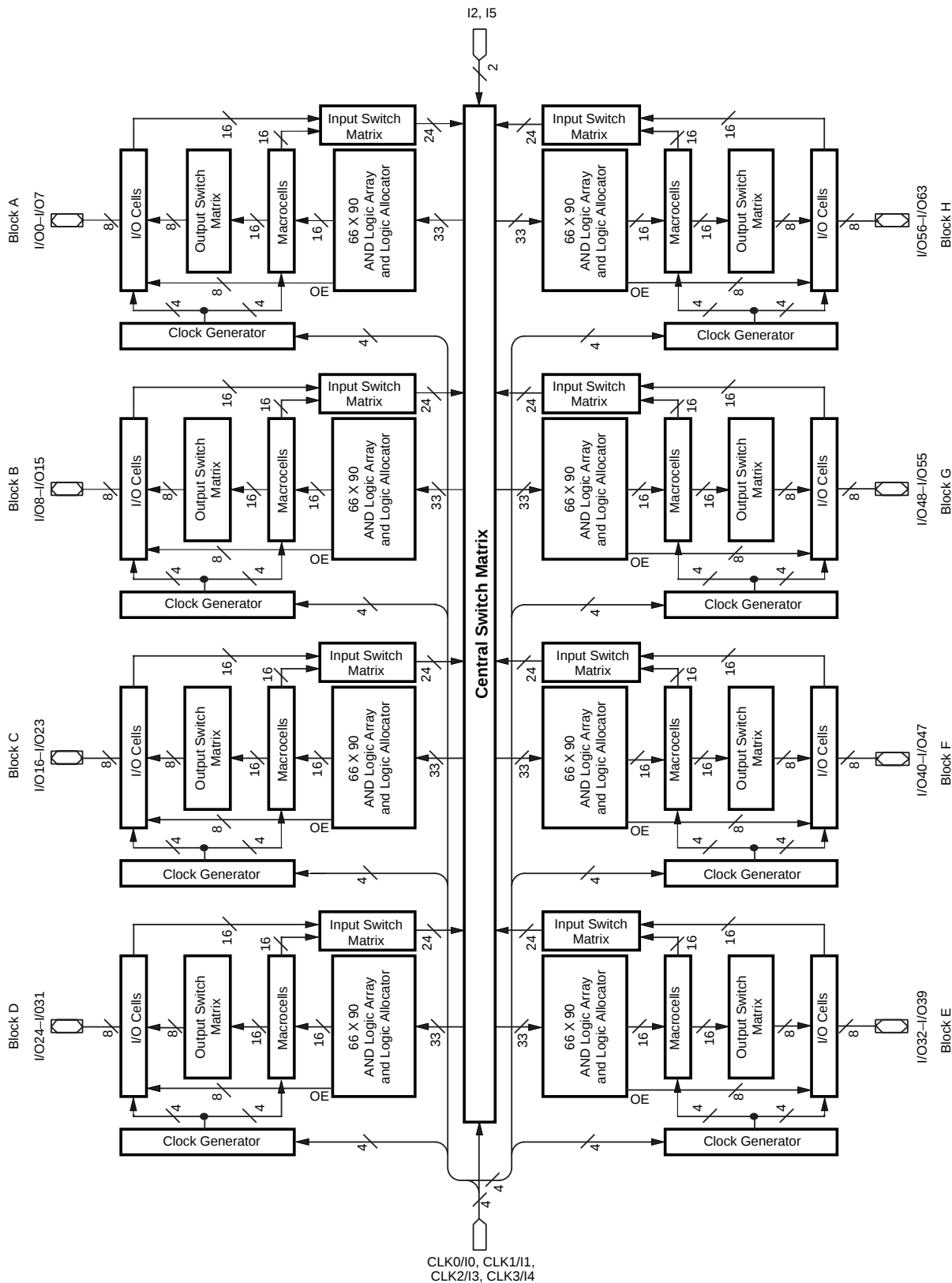
17466H-042

BLOCK DIAGRAM – M4A(3,5)-96/48



17466G-021

BLOCK DIAGRAM – M4A(3,5)-128/64



17466H-022

ABSOLUTE MAXIMUM RATINGS

M4A3

Storage Temperature. -65°C to +150°C
 Ambient Temperature
 with Power Applied. -55°C to +100°C
 Device Junction Temperature. +130°C
 Supply Voltage
 with Respect to Ground. -0.5 V to +4.5 V
 DC Input Voltage. -0.5 V to 6.0 V
 Static Discharge Voltage. 2000 V
 Latchup Current ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
 Operating in Free Air. 0°C to $+70^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)
 Operating in Free Air. -40°C to $+85^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +3.0 V to +3.6 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions		Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min}$ $V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -100\ \mu\text{A}$	$V_{CC} - 0.2$			V
			$I_{OH} = -3.2\ \text{mA}$	2.4			V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 1)	$I_{OL} = 100\ \mu\text{A}$			0.2	V
			$I_{OL} = 24\ \text{mA}$			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs		2.0		5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs		-0.3		0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 3.6\ \text{V}$, $V_{CC} = \text{Max}$ (Note 2)				5	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0\ \text{V}$, $V_{CC} = \text{Max}$ (Note 2)				-5	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 3.6\ \text{V}$, $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 2)				5	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0\ \text{V}$, $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 2)				-5	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5\ \text{V}$, $V_{CC} = \text{Max}$ (Note 3)		-15		-160	mA

Notes:

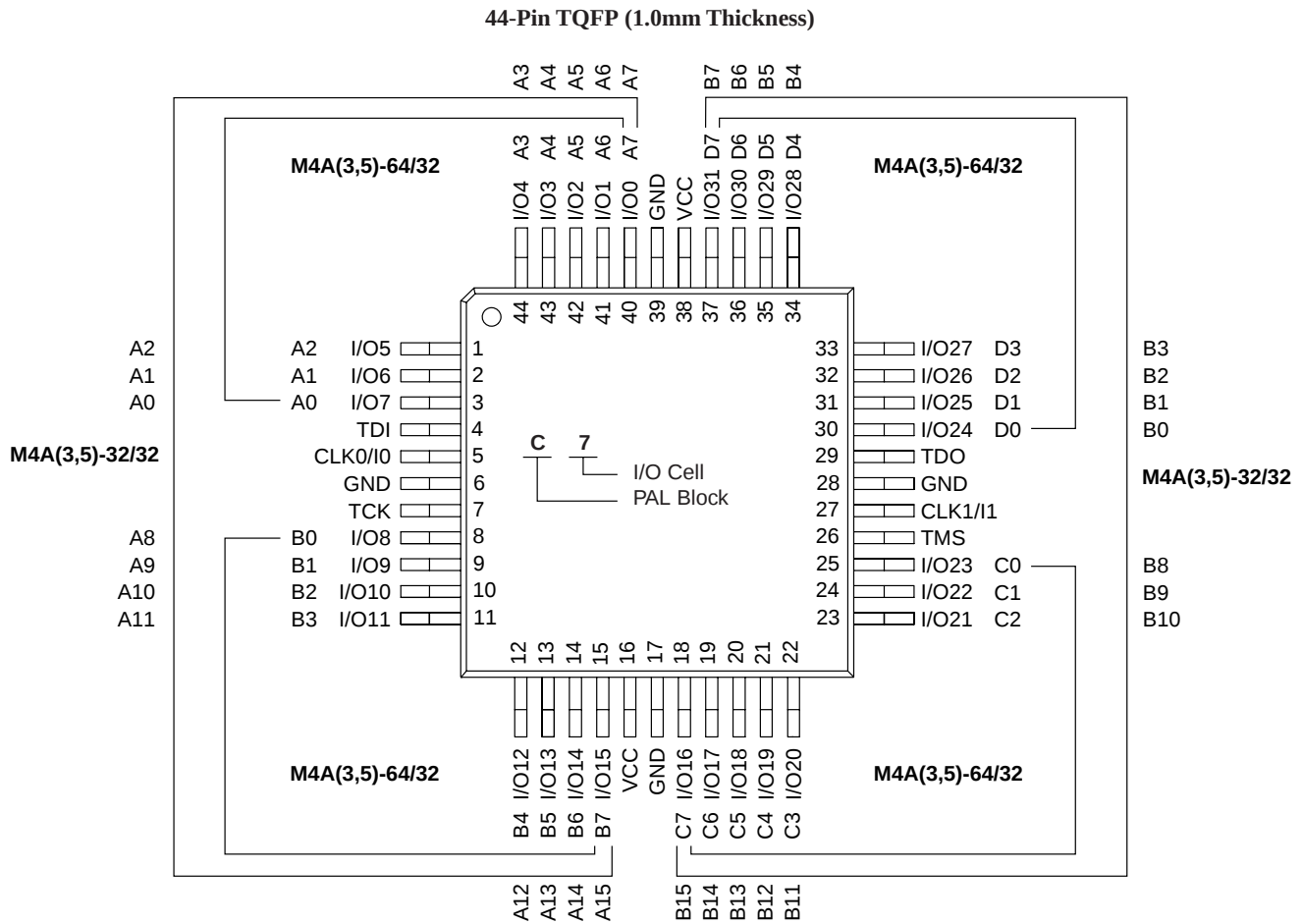
1. Total I_{OL} for one PAL block should not exceed 64 mA.
2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Notes:

1. See "MACH Switching Test Circuit" document on the Literature Download page of the Lattice web site.
2. This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.

44-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View



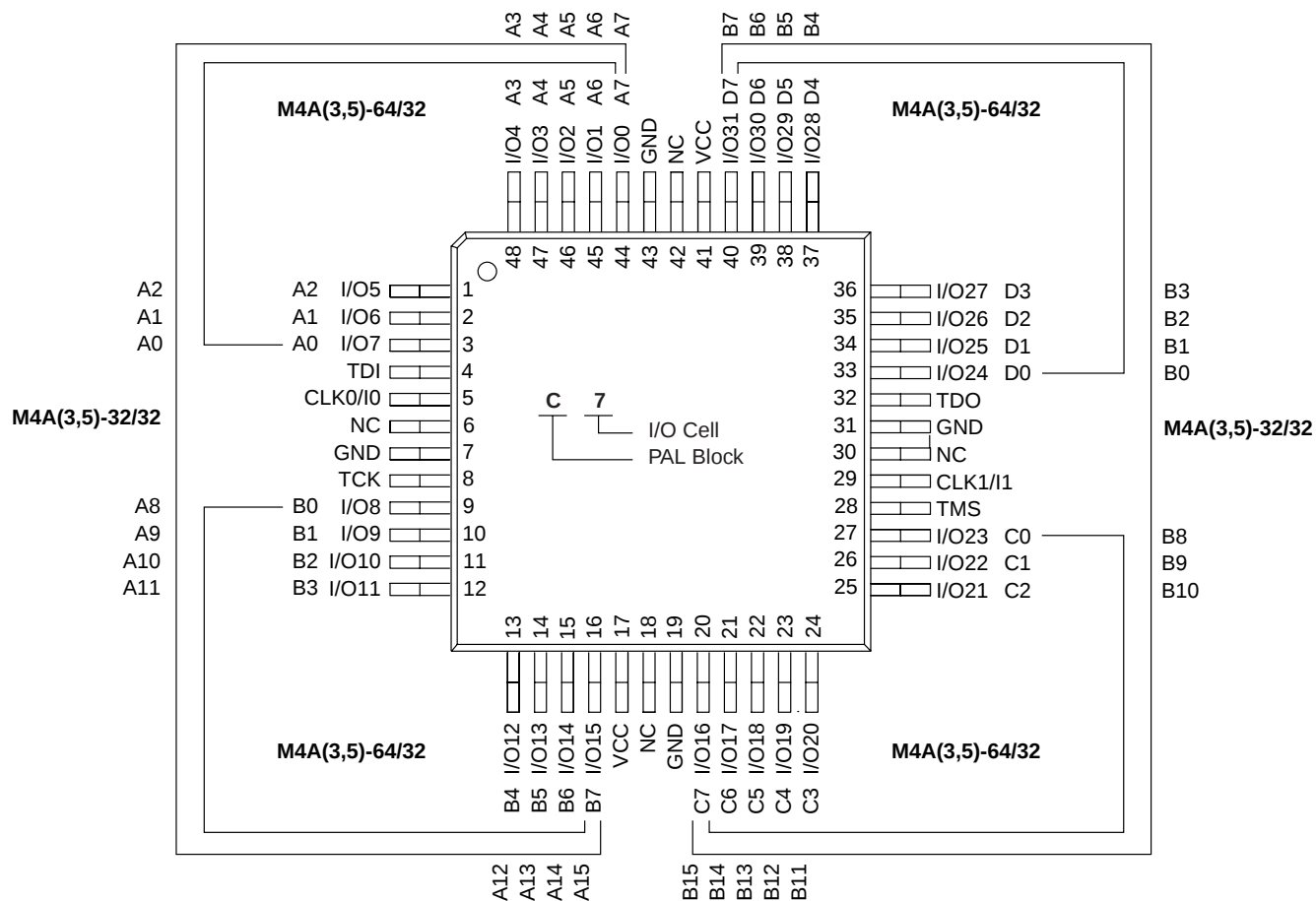
PIN DESIGNATIONS

- CLK/I = Clock or Input
- GND = Ground
- I/O = Input/Output
- V_{CC} = Supply Voltage
- TDI = Test Data In
- TCK = Test Clock
- TMS = Test Mode Select
- TDO = Test Data Out

48-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

48-Pin TQFP (1.4mm Thickness)



17466G-028

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

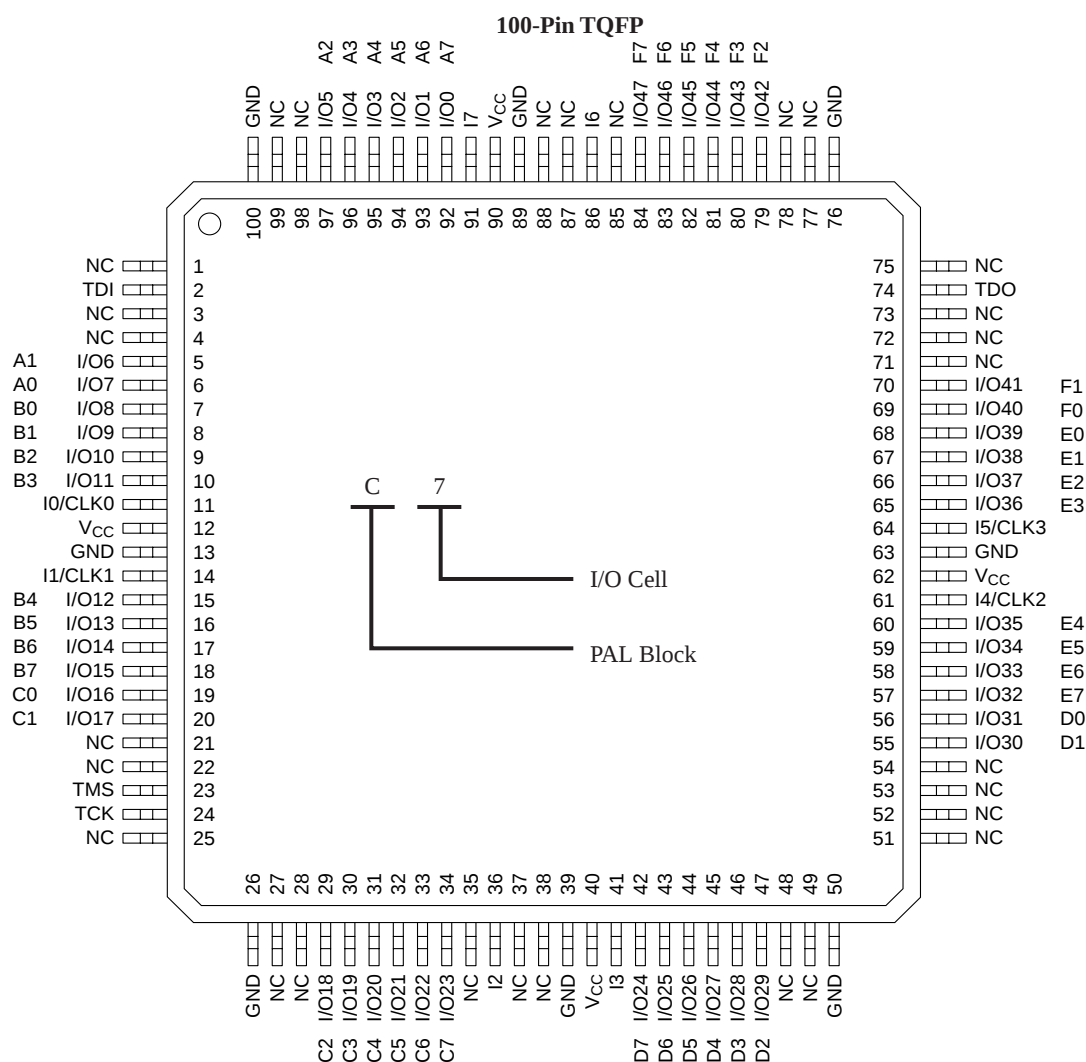
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-96/48)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

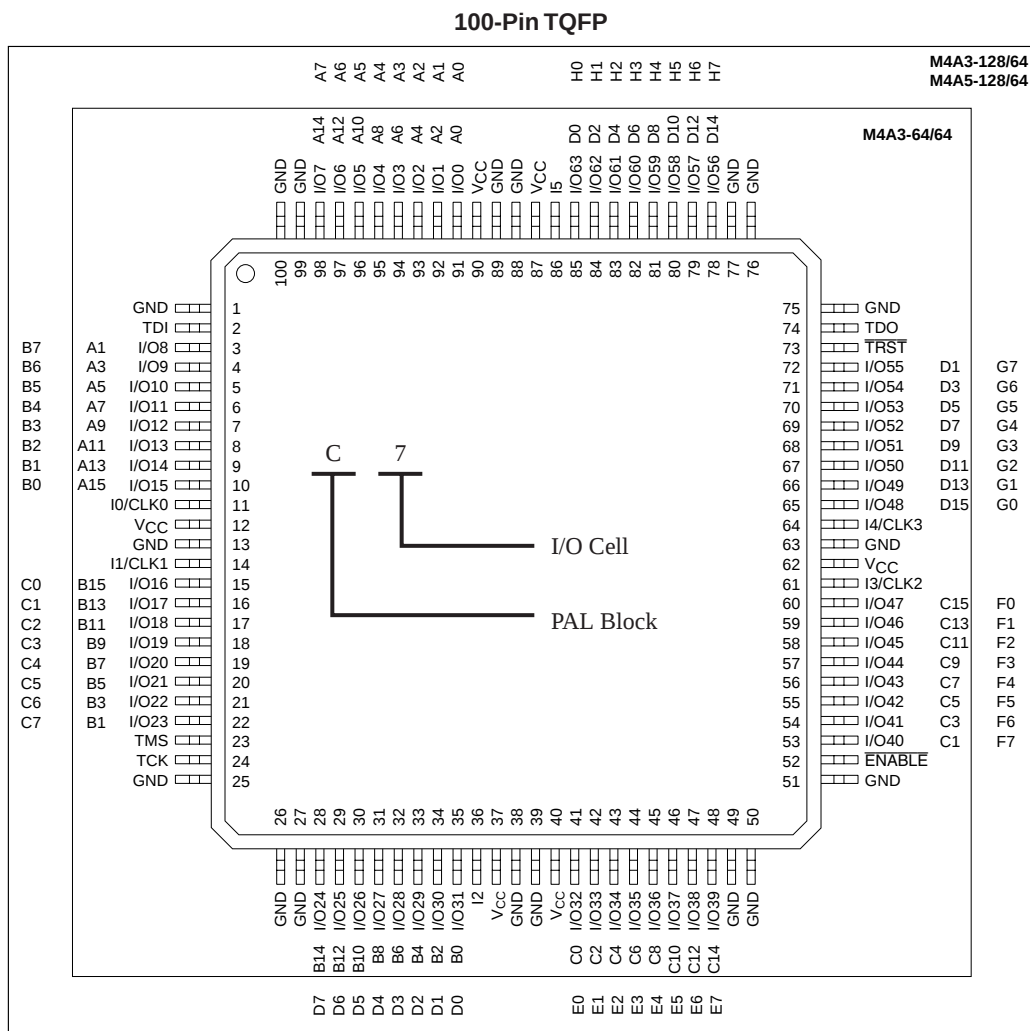
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN TQFP CONNECTION DIAGRAM (M4A3-64/64 AND M4A(3,5)-128/64)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

TRST = Test Reset

ENABLE = Program

256-BALL BGA CONNECTION DIAGRAM (M4A3-256/128)

Bottom View

256-Ball BGA

	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	N/C	GND	I/O108 N4	I/O105 N1	GND	I/O100 M4	I/O96 M0	GND	GND	GND	GND	I/O95 L0	I/O91 L4	GND	I/O87 K0	N/C	GND	GND	GND	A
B	GND	I/O113 O6	N/C	I/O109 N5	I/O106 N2	I/O103 M7	I/O102 M6	I/O98 M2	N/C	I11	N/C	N/C	I/O93 L2	I/O89 L6	I/O88 L7	I/O85 K2	I/O83 K4	I/O82 K5	N/C	GND	B
C	I/O116 O3	N/C	VCC	TRST	I/O111 N7	I/O107 N3	I/O104 N0	I/O101 M5	I/O97 M1	N/C	I10	I/O94 L1	I/O90 L5	I/O86 K1	I/O84 K3	I/O80 K7	ENABLE	VCC	I/O78 J6	I/O74 J2	C
D	I/O120 P7	I/O117 O2	I/O112 O7	VCC	VCC	I/O110 N6	VCC	N/C	I/O99 M3	N/C	I9	I/O92 L3	N/C	VCC	I/O81 K6	VCC	VCC	I/O79 J7	I/O75 J3	I/O71 I7	D
E	I/O123 P4	I/O119 O0	I/O114 O5	TDI	PIN DESIGNATIONS CLK = Clock GND = Ground I = Input I/O = Input/Output N/C = No Connect VCC = Supply Voltage TDI = Test Data In TCK = Test Clock TMS = Test Mode Select TDO = Test Data Out TRST = Test Reset ENABLE = Program C7 I/O Cell PAL Block												TDO	I/O77 J5	I/O72 J0	I/O68 I4	E
F	GND	I/O122 P5	I/O118 O1	I/O115 O4													I/O76 J4	I/O73 J1	I/O69 I5	GND	F
G	I12	I/O125 P2	I/O121 P6	VCC													VCC	I/O70 I6	I/O65 I1	I8	G
H	GND	I/O127 P0	I/O126 P1	I/O124 P3													I/O67 I3	I/O66 I2	I/O64 I0	GND	H
J	N/C	N/C	N/C	I13													I7	N/C	N/C	N/C	J
K	GND	CLK3	N/C	N/C													N/C	N/C	CLK2	N/C	K
L	N/C	CLK0	N/C	N/C													N/C	N/C	CLK1	GND	L
M	N/C	N/C	N/C	I0													I6	N/C	I/O63 H0	I/O62 H1	M
N	GND	I/O0 A0	I/O2 A2	I/O3 A3													I/O60 H3	I/O61 H2	I/O59 H4	GND	N
P	I1	I/O1 A1	I/O6 A6	VCC													VCC	I/O57 H6	I/O58 H5	I5	P
R	GND	I/O5 A5	I/O9 B1	N/C	I/O51 G4	I/O54 G1	I/O56 H7	GND	R												
T	I/O4 A4	I/O8 B0	I/O12 B4	TCK	TMS	I/O50 G5	I/O55 G0	N/C	T												
U	I/O7 A7	I/O11 B3	I/O15 B7	VCC	VCC	I/O18 C5	VCC	I/O24 D7	I/O29 D2	I2	N/C	I/O35 E3	N/C	VCC	N/C	VCC	VCC	I/O48 G7	I/O53 G2	N/C	U
V	I/O10 B2	I/O13 B5	VCC	I/O16 C7	I/O17 C6	I/O21 C2	I/O23 C0	I/O27 D4	I/O31 D0	I3	N/C	I/O33 E1	I/O37 E5	I/O41 F1	I/O43 F3	I/O46 F6	I/O47 F7	VCC	I/O52 G3	N/C	V
W	GND	I/O14 B6	N/C	N/C	I/O19 C4	I/O22 C1	I/O25 D6	I/O28 D3	N/C	N/C	I4	N/C	I/O34 E2	I/O38 E6	I/O39 E7	I/O42 F2	I/O45 F5	N/C	I/O49 G6	GND	W
Y	GND	GND	GND	N/C	I/O20 C3	GND	I/O26 D5	I/O30 D1	GND	GND	GND	GND	I/O32 E0	I/O36 E4	GND	I/O40 F0	I/O44 F4	GND	N/C	GND	Y
	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

17466G-045

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-384/192)

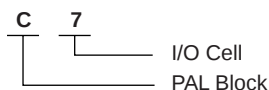
Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O175 FX7	I/O181 GX5	I/O180 GX4	I/O177 GX1	I/O166 EX6	I/O164 EX4	I/O191 HX7	I/O186 HX2	I/O1 A1	I/O3 A3	CLK0	I/O25 D1	I/O29 D5	I/O31 D7	I/O10 B2	I/O12 B4	A
B	I/O173 FX5	I/O174 FX6	I/O182 GX6	I/O179 GX3	I/O167 EX7	I/O165 EX5	I/O160 EX0	I/O187 HX3	I/O0 A0	I/O5 A5	I/O7 A7	I/O26 D2	I/O8 B0	I/O11 B3	I/O13 B5	N/C	B
C	I/O171 FX3	I/O172 FX4	N/C	I/O183 GX7	I/O178 GX2	I/O162 EX2	I/O163 EX3	I/O189 HX5	I/O184 HX0	I/O6 A6	I/O28 D4	I/O30 D6	I/O15 B7	I/O14 B6	TDI	I/O23 C7	C
D	I/O150 CX6	I/O151 CX7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O22 C6	I/O21 C5	D
E	I/O148 CX4	N/C	I/O170 FX2	VCC	I/O168 FX0	169 FX1	I/O190 HX6	CLK3	I/O188 HX4	I/O2 A2	I/O24 D0	N/C	GND	I/O20 C4	I/O19 C3	I/O47 F7	E
F	I/O144 CX0	I/O149 CX5	I/O147 CX3	GND	I/O146 CX2	I/O145 CX1	I/O176 GX0	I/O161 EX1	I/O185 HX1	I/O4 A4	I/O27 D3	I/O18 C2	VCC	I/O16 C0	I/O46 F6	I/O45 F5	F
G	I/O155 DX3	I/O158 DX6	I/O157 DX5	VCC	I/O156 DX4	I/O159 DX7	VCC	GND	GND	VCC	I/O17 C1	I/O44 F4	GND	I/O42 F2	I/O41 F1	I/O39 E7	G
H	I/O152 DX0	I/O154 DX2	I/O153 DX1	GND	I/O128 AX0	I/O129 AX1	GND	VCC	VCC	GND	I/O43 F3	I/O40 F0	VCC	I/O36 E4	I/O35 E3	I/O34 E2	H
J	I/O130 AX2	I/O131 AX3	I/O132 AX4	GND	I/O134 AX6	I/O133 AX5	GND	VCC	VCC	GND	I/O38 E6	I/O37 E5	GND	I/O57 H1	I/O56 H0	I/O58 H2	J
K	I/O135 AX7	I/O136 BX0	I/O137 BX1	VCC	I/O139 BX3	I/O138 BX2	VCC	GND	GND	VCC	I/O33 E1	I/O32 E0	VCC	I/O63 H7	I/O62 H6	I/O48 G0	K
L	I/O140 BX4	I/O141 BX5	I/O143 BX7	GND	I/O114 O2	I/O142 BX6	I/O98 M2	I/O91 L3	I/O67 I3	I/O69 I5	I/O60 H4	I/O59 H3	GND	I/O51 G3	I/O52 G4	I/O49 G1	L
M	I/O112 O0	I/O113 O1	I/O115 O3	GND	I/O123 P3	I/O121 P1	I/O100 M4	I/O90 L2	I/O66 I2	I/O80 K0	I/O83 K3	I/O61 H5	VCC	I/O76 J4	I/O55 G7	I/O50 G2	M
N	I/O116 O4	I/O117 O5	I/O119 O7	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O72 J0	I/O53 G5	N
P	I/O118 O6	I/O109 N5	I/O110 N6	I/O111 N7	I/O124 P4	I/O122 P2	I/O101 M5	I/O89 L1	I/O93 L5	I/O94 L6	I/O71 I7	I/O84 K4	I/O87 K7	TMS	I/O73 J1	I/O54 G6	P
R	I/O108 N4	I/O107 N3	I/O104 N0	I/O127 P7	I/O120 P0	I/O102 M6	I/O99 M3	I/O96 M0	I/O92 L4	I/O64 I0	I/O68 I4	I/O81 K1	I/O85 K5	I/O79 J7	I/O75 J3	I/O74 J2	R
T	I/O106 N2	I/O105 N1	I/O126 P6	I/O125 P5	I/O103 M7	CLK2	I/O97 M1	I/O88 L0	CLK1	I/O95 L7	I/O65 I1	I/O70 I6	I/O82 K2	I/O86 K6	I/O78 J6	I/O77 J5	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out



m4a3.384.192_256bga